EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	37	fas near microe	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/11 11:25
S1	68	438/15 and trim$5 and test$5	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/07 15:11
S2	0	438/15 and trim$5 and test$5 and undercoat$5	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/04 10:52
S3	31	438/15 and (trim$5 near form$5) and test$5	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/05 09:06
S4	2	438/15 and (trim$5 adj circuit) and (test$5 probe)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/05 09:23
S6	5	("3768157" | "3827142" | "4439754").PN. OR ("6352880"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 09:38
S7	1	("6472897").PN. OR ("6872582"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 09:42
S8	30	("3890610" | "4150366" | "4225878" | "4335371" | "4412241" | "4665356" | "4713602" | "4823320" | "5079516" | "5353028" | "5361001" | "5426616" | "5563549" | "5568083" | "5663589" | "5675280" | "5682049" | "5757264" | "5768290" | "5771012").PN. OR ("6472897"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 10:36
S9	2	(438/14-18.ccls. 257/529,530,50. ccls.) and trim$5 and ((wafer substrate) near (coat mold))	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 10:41
S10	23	(438/14-18.ccls. 257/529,530,50. ccls.) and trim$5 and ((wafer substrate) same (coat mold))	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 11:22
S11	75	seto.in. and trim$5	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 11:22

S12	8	"6638863"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/05 11:49
S13	2	"20010045645"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/05 11:51
S14	2	"20020025603"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/05 11:52
S15	2	"20030085445"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/05 11:54
S16	63	(trim$5 same fuse) and (package same (coat mold resin epox$5 polyimide))	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/05 13:35
S17	60	(trim$5 same fuse) and (wafer same (coat mold resin epox$5 polyimide))	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/06 14:53
S18	18	("4896055" | "5617366").PN. OR ("5768290").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/06 14:22
S19	2	"20030169064"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/06 14:49
S20	2179	(wafer same package same (coat mold resin epox$5 polyimide))	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/06 14:54
S21	1	(trim adj pad) and (bump ball c4) and (wafer same package same (coat mold resin epox$5 polyimide))	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/07 07:44
S22	7	("5329423" | "5736456" | "5767010" | "5773359" | "5937320" | "5977632").PN. OR ("6327158"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/06 15:15
S23	3	"6327158"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/06 15:25

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S24	69	(kelkar vishwanath) and trim$5	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/06 15:34
S26	108	(pirkle harbert reeves) and trim$5 and (bump ball c4) and (wafer substrate)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/06 15:39
S27	179	(texas adj instruments) and trim$5 and (bump ball c4) and (wafer substrate)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/06 16:12
S28	79	(national adj semiconductor) and trim$5 and (bump ball c4) and (wafer substrate)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/07 07:42
S29	241	(national adj semiconductor) and trim$5 and (bump ball c4)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/07 07:42
S30	161	trim$5 and (bump ball c4) and (wafer same package same (coat mold resin epox$5 polyimide))	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/07 09:10
S31	1628	438/15	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/07 09:10
S32	811	438/15.ccls.	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/07 09:23
S33	394	wafer and (fuse same (coat$5 mold$5 package)) and thick$5 and (polyi$6 epox$4)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/08 09:25
S34	5	wafer and (((trim$5 fuse) adj (contact pad)) same (coat$5 mold$5 package)) and thick$5 and (polyi$6 epox$4)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/07 15:28
S35	89	wafer and (flip adj chip) and (fuse same (coat$5 mold$5 package)) and thick$5 and (polyi$6 epox$4)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 09:43
S36	0	(trim adj pad) same (coat mold) same (polyimide epoxy)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 09:44

S37	2	(trim adj pad) same (coat mold) and (polyimide epoxy)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 09:45
S38	2	((fuse trim) adj pad) same (coat mold) and (polyimide epoxy)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 09:45
S39	1167	438/612-613.ccls. and (polyimide epoxy) and thick$5	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 11:13
S40	30	438/612-613.ccls. and (polyimide epoxy) and thick$5 and trim$5	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 11:20
S41	1066	438/612-613.ccls. and (polyimide epoxy) and thick$5 and (bump ball c4)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 11:21
S42	1066	438/612-613.ccls. and (polyimide epoxy) and thick$5 and (bump ball c4 bga)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 16:57
S43	0	438/612-613.ccls. and ((polyimide epoxy) near (directly adj on adj (substrate active))) and thick$5 and (bump ball c4 bga)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 16:58
S44	0	438/612-613.ccls. and ((polyimide epoxy) near (directly adj on adj (substrate active)))	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 16:58
S45	0	438/612-613.ccls. and ((polyimide epoxy) near direct near (substrate active))	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 16:59
S46	0	438/612-613.ccls. and ((polyimide epoxy) near on near (substrate active))	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 16:59
S47	105	438/612-613.ccls. and ((polyimide epoxy) near (substrate active))	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 17:23
S48	25	438/612-613.ccls. and ((polyimide epoxy) near (underfill undercoat))	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 17:23
S49	3	"6732913" "6592019"	USPAT	OR	ON	2006/04/10 17:45

S50	14	"20010040290" "6413851" "20030219966" "20030129822" "20030096494" "20020061641"	USPAT	OR	ON	2006/04/10 17:49
S51	20	"20010040290" "6413851" "20030219966" "20030129822" "20030096494" "20020061641"	US-PGPUB; USPAT	OR	ON	2006/04/10 17:49
S52	2	"20030127502"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2006/04/10 18:00